



PATENT

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL, POSTAGE PREPAID, IN AN ENVELOPE ADDRESSED TO COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231, ON

NOVEMBER 26, 2002

Mark B. Quatt

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paleari et al.

Serial No.: 09/807,210

Filing Date: July 16, 2001

Title: New High Resistance Heat-Shrinkable Thermoplastic Film

Docket No: 42992-01

Examiner: Patterson, Marc A.

Group Art Unit: 1772

Response under 37 C.F.R. § 1.111

Commissioner For Patents
Washington, D. C. 20231

Sir:

This response is being filed in response to the Office Action mailed August 26, 2002, which is due for response on November 26, 2002.

Please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 1 to 10.

Please add the following claims:

11. A multi-layer heat-shrinkable film comprising:
- a) an outer heat-sealing layer comprising at least one polyolefin;
 - b) an outer abuse layer comprising a polyamide with a melting point of at least 175 °C; and
 - c) an intermediate gas barrier layer comprising vinylidene chloride copolymer; wherein all the layers of the film are oriented.
12. The multi-layer heat-shrinkable film of claim 11 wherein the polyamide of the outer abuse layer has a melting point of between 175 °C and 250°C.